Contents

Introduction

What is surface mount technology?	3
S. McClelland, IFS Publications, UK	3
	7
World Scene: Japan S. McClelland, IFS Publications, UK	7
SMT – the Timex experience S. McClelland, IFS Publications, UK	11
Surface mount technology design	
Surface mount technology – a designer's perspective R.J. Brandt and R.J. Mnich, AT & T Information Systems, USA	17
Printed circuit board substrates S. Jones, Manchester Circuits, UK	23
Integrated circuit design for surface mount technology P. McCormick, Texas Instruments Ltd, UK	29
Computer-aided design system requirements for surface mount technology design L.E. Rohde, Tektronix Inc., USA	35
Selecting a computer-aided engineering system for surface mount technology A. Schatorjé, Philips Centre for Manufacturing Technology, The Netherlands	53
Designing testable printed circuit boards which utilise surface mount devices R.G. Bennetts, Bennetts Associates, UK	61
World scene: UK D. Boswell, DTI/Industry Surface Mount Club, UK	71
A low-risk approach to the introduction of surface mount technology I.C. White, Mars Electronics, UK	75
Surface mount technology manufacture	
Manufacturing implications of surface mount technology A.G. Kenney, Cambridge Consultants Ltd, UK	83
 Surface mount technology assembly: Quality and reliability in placement P.S. Grundy, Siemens Ltd, UK 	89
 ✓ Soldering techniques for manufacturing surface mount devices T. Takei, OKI Electric Industry Co. Ltd, Japan 	95
 Screen printing for surface mount A. Hobby, DEK Printing Machines Ltd, UK 	103



Cleaning surface mounted device assemblies W. Lambert, Kerry Ultrasonics Ltd, UK	109
World scene: Germany R.D. Schraft and E.M. Wolf, Fraunhofer-Institut für Produktionstechnik und Automatisierung (IPA), West Germany	113
Case study: MRP Electronics Ltd — a start-up in surface mount technology S. McClelland, IFS Publications, UK	123
Case Study: AB Electronics – a sub-contractor's experience R. Carrie, AB Electronics (Rogerstone) Ltd, UK	127
Testing, rework, quality and reliability	
Testing surface mount technology boards P.F. Macready, British Telecom Fulcrum, UK	139
The sensitivity of surface mount technology to component quality B.P. Richards, GEC Research Ltd, UK	143
Computer modelling of package/substrate assemblies for solder joint reliability A.P. Moore, R.W. Elston and D.J. Burrows, GEC-Marconi Research Centre, UK	155
Rework processing S. McClelland, IFS Publications, UK	167
Quality case study: The case of the cracked capacitors M.L. Martel, Conceptronic Inc, USA	169
Case study: Implementing surface mount technology into telecommunication products M.L. Barton, Rockwell International, USA	173
Surface mount technology – the challenge to management	
Surface mount technology – the management of change M.A. Phillips, Plessey Networks and Office Systems Ltd, UK	179
Surface mount technology and Just-in-Time H. Metcalf and J. Jacques, The Foxboro Company, USA	183
Training for surface mount technology M. Cole, Engineering Industry Training Board, UK and R.J.D. Willis, Dimension 2 Technology plc, UK	185
Case study: Quality and automation at Rank Xerox N. Price, Rank Xerox Ltd, UK and S. McClelland, IFS Publications, UK	189
The future	
Future trends in surface mount and high density interconnection technology D.J. Pedder, Plessey Research (Caswell) Ltd, UK	197

Appendix

Appendix: Passive components S. McClelland, IFS Publications, UK

Authors' organisations and addresses

209

213

217

Source of material